



CBW

Copper Bonding Wire

Copper wire has become one of the preferred materials for wire bonding interconnects in many semiconductor and microelectronic applications. Copper bonding wire is initially designed as a substitution for gold bonding wire, and its demand is growing faster as developing wire bonding technology enables it to extend its capability.

TYPE : HS-CL

Why copper bonding wire is preferred?

Functional Demand

To maximize the package's operating speed
Low electrical resistance ($Ag < Cu < Au < Al$)

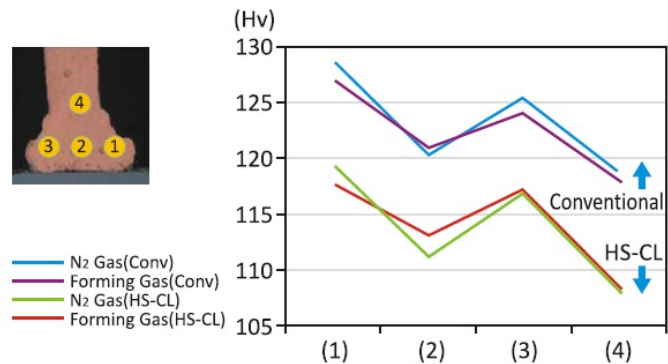
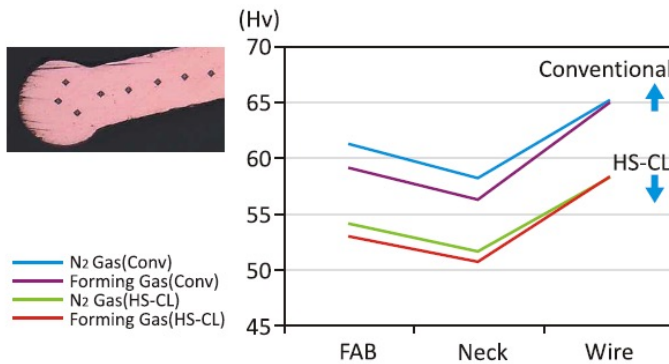
Market Demand

To minimize package manufacturing cost
(The lowest material cost)

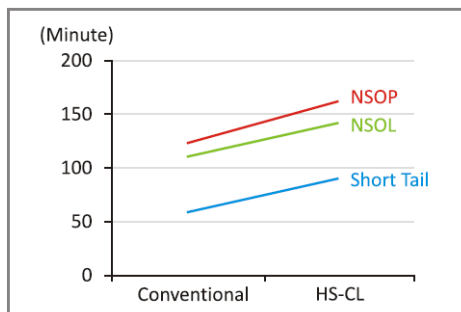
Superior Performance of LT Metal's Copper Bonding Wire

Softest copper bonding wire

Hardness Comparison (Before & After Bonding)



Enhances Yield & Workability



Test Vehicle

Device : MLF

Bonding Wire : HS-CL (25um)

Capillary : TD32 HD12 CD 15

Wire Bonder : ASM E60AP

Ball Size : Max 50um

Bonding Parameters : Minimized values for test

LT Metal Cu wire acquired good performance in bump ball application, BSOB (SSB).

